On page 6, on a separate line immediately following the above inserted paragraph and before line 9, please insert the following header:

-- DETAILED DESCRIPTION OF THE INVENTION --.

On a separate page, after page 13, please insert the enclosed Abstract of the Disclosure.

In the Claims

Please cancel Claim 1, without prejudice.

Please add the following new claims:

-- 7. (NEW) A process for producing a card body comprising

forming a component layer comprising one or more electronic circuits or transponders using a thermoplastic hot-melt adhesive, wherein the hot-melt adhesive has a processing viscosity ranging from 100 mPa·s to 100,000 mPa·s and at least partially encapsulates the electronic circuits or transponders.

8. (NEW) The process of claim 7 wherein the forming of the component layer is carried out in an injection molding process at an injection molding pressure ranging from 1 bar to 50 bar and an injection molding temperature ranging from 80°C to 250°C.

9. (NEW) The process of claim 8 wherein the injection molding temperature ranges from 100°C to 230°C.

10. (NEW) The process of claim 9 wherein the injection molding pressure ranges from 10 bar to 30 bar.

11. (NEW) The process of claim 8 wherein the forming comprises providing an electronic circuit on a support film and injecting the hot-melt adhesive onto the electronic circuit in an injection mold.

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12. (NEW) The process of claim 8 wherein the forming comprises applying a film of the hot-melt adhesive in an injection mold, placing the electronic component on the film, and injecting a second amount of the hot-melt adhesive onto the electronic component to encapsulate the electronic component in the hot-melt adhesive.

13. (NEW) The process of claim 8, wherein the hot-melt adhesive comprises a polyamide, polyurethane, polyester, atactic polypropylene, ethylene-vinyl acetate copolymers, or low molecular mass polyethylene copolymers, or combinations thereof.

14. (NEW) A transponder or card body produced by the process of claim 8.

15. (NEW) The transponder or card body of claim 14 wherein the card body is a smart card.

16. (NEW) The process of claim 7, wherein the hot-melt adhesive comprises a polyamide, polyurethane, polyester, atactic polypropylene, ethylene-vinyl acetate copolymers, or low molecular mass polyethylene copolymers, or combinations thereof.

17. (NEW) A transponder or card body produced by the process of claim 7.

18. (NEW) The transponder or card body of claim 17 wherein the card body is a smart card. --